NIINO LAB.

[New Manufacturing Technology for New Device]

Design-Led X Platform Department of Mechanical and Biofunctional Systems Social Cooperation Program, Base Technology for Future Robots

Additive Manufacturing Science

Department of Precision Engineering

http://lams.iis.u-tokyo.ac.jp

3D Printing and MID (Molded Interconnect Device)

This lab aims to create novel mechanical and electrical devices with novel manufacturing technology. To do this, we emphasize on functional 3D geometrical shape made of combined material. In detail, we focus on Additive Manufacturing (AM) and Molded Interconnect Device (MID) and their application.



Additive Manufacturing (AM)

New AM Process

<u>AM Application</u>

- Process Development in Laser Sintering Fabrication
- Laser Sintering Process for High Performance Polymer



Low temperature laser sintering



Eiffel tower using PEEK (High performance plastic)



Microscopic object fabrication

• Laser Sintering Fabrication of Tissue Engineering Scaffolds

Laser Sintering Fabrication realizing High Porosity and Intensity



Molded Interconnect Device (MID)



Fabrication process for MIDs

• MID fabrication process using sacrificial body

MID Application on Mechatronic Devices





3D Tissue engineering scaffold

• Application of Photonic Device using Laser Sintering Fabrication





Additive Manufacturing of Metal-Plastic Complex Body





Fabrication of Amorphous Structures (Photonic Fractal)

Circuit pattern transfer to inner surface using sacrificial body.

MID Application

Circuit pattern transfer to inner surface of objects using sacrificial material



Sacrificial body

+ Soft etching



 MID Application on Static Electric Motor.



Injection Molded Functional Fluid Channel



MID with Micro Fluid Channel



MID technology





